

REMARKS

Claim 1-7 are pending. Claims 4 and 5 were previously withdrawn. Claims 1 and 2 are currently amended. Claims 6 and 7 are new.

Claims 1-3 were rejected under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 5,471,366 (Ozawa). Applicant submits that claim 1 should be allowable for at least the following reasons.

First, claim 1 has been amended to recite that: 1) the semiconductor element is fixed to a first main surface of the mounting substrate and electrically connected to a first conductive pattern on the first main surface; and 2) a second conductive pattern is formed on a second main surface of the mounting substrate that is opposite the first main surface. An example of that is shown in FIGs. 1A and 1B, where semiconductor element 13 is fixed to a first main surface of the mounting substrate 11 and is electrically connected to a first conductive pattern 12 on that first main surface. A second conductive pattern 16 is formed on a second main surface 11 of the mounting substrate that is opposite the first main surface. No new matter has been added. By implementing the features now recited in claim 1, a more compact semiconductor device may be provided, because electrical connections to the semiconductor element 13 can be made at the second main surface of the mounting substrate 11 that is opposite the first main surface where the semiconductor element is fixed.

In contrast, the multichip module disclosed in the Ozawa patent includes a number of interconnection leads 37 for the semiconductor chips 81₁, 81₂ that extend outward from the sides of the module 80. (*See* FIG. 7) The Ozawa patent does not disclose or suggest a second conductive pattern on a second main surface of a mounting substrate that is opposite a first main surface where the semiconductor chips 81₁, 81₂ are mounted.

Claim 1 should be allowable for at least that reason.

Additionally, claim 1 has been amended to recite that a side surface of the sealing resin and a side surface of the mounting substrate are located on the same plane. An example of that is

shown in FIG. 1B where the side surfaces of the sealing resin 18 are in the same plane as corresponding side surfaces of the mounting substrate 11. No new matter has been added. Certain implementations of that feature contribute to reducing the overall size of a semiconductor device. The Ozawa patent does not disclose or suggest that feature. Referring, for example, to FIG. 7 of the Ozawa patent, it is clear that none of the side surfaces of the resin package body 34 are in the same plane as any side surface of the substrate 31. Nor is that feature disclosed elsewhere in the Ozawa patent.

Claim 1 should be allowable for that additional reason as well.

Claims 2 and 3 depend from claim 1 and, therefore, should be allowable for at least the same reasons as claim 1.

Claims 6 and 7 also depend from claim 1 and, therefore, should be allowable for at least the same reasons as claim 1.

It is believed that all of the pending claims have been addressed. However, the absence of a reply to a specific rejection, issue or comment does not signify agreement with or concession of that rejection, issue or comment. In addition, because the arguments made above may not be exhaustive, there may be reasons for patentability of any or all pending claims (or other claims) that have not been expressed. Finally, nothing in this paper should be construed as an intent to concede any issue with regard to any claim, except as specifically stated in this paper, and the amendment of any claim does not necessarily signify concession of unpatentability of the claim prior to its amendment.


Enclosed is a \$790 check for the Request for Continued Examination fee. Please apply any other charges or credits to deposit account 06-1050.

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